

## Excellent Integrated System Limited

Stocking Distributor

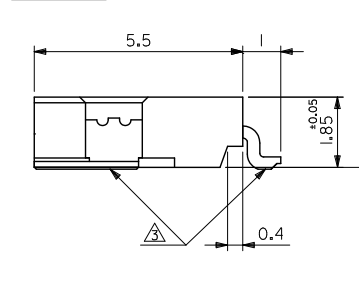
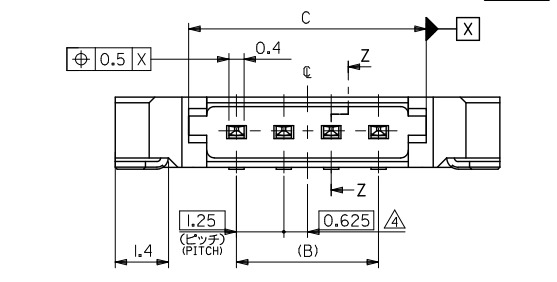
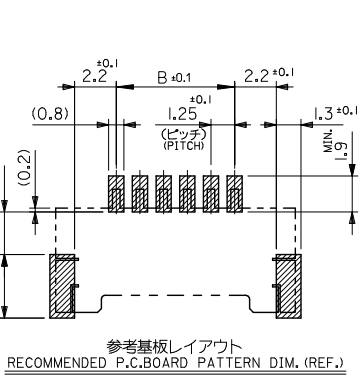
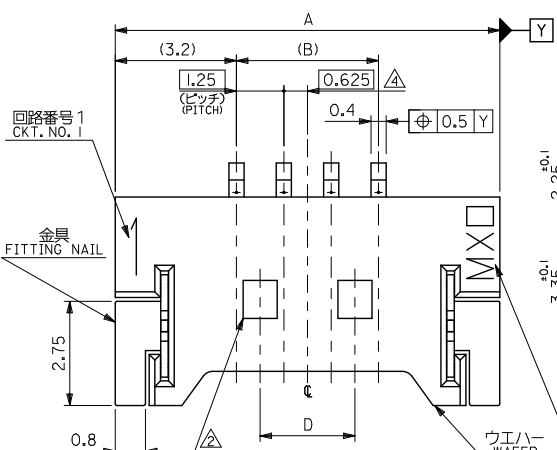
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)  
[0537800670](#)

For any questions, you can email us directly:

[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)

10 9 8 7 6 5 4 3 2 1



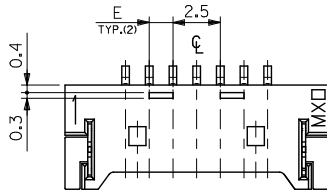
**注記 NOTES**

1. 嵌合相手: 51146 シリーズ  
MATES WITH: 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、上方向に 0.05MAX、下方向 0.15MAX、とし、20極以下の相互のパラッキ量は 0.1MAX、とする。  
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]: UPPER DIRECTION 0.05MAX, LOWER DIRECTION 0.15MAX, OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
4. 偶数極の製品に適用。  
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL  
ウエハー WAFER: PPS, UL94V-0  
ピン: リン青銅 PIN: PHOSPHOR BRONZE  
コンタクト部: 金メッキ 0.2 マイクロメートル以上  
CONTACT AREA: GOLD 0.2 MICROMETER MINIMUM  
テール部: 錫メッキ 3.0 マイクロメートル以上  
TAIL AREA: TIN 3.0 MICROMETER MINIMUM  
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
金具: リン青銅 FITTING NAIL: PHOSPHOR BRONZE  
錫メッキ 3.0 マイクロメートル以上  
TIN 3.0 MICROMETER MINIMUM  
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
6. 本製品は 53780-\*\*10/-\*\*18 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53780-\*\*10/-\*\*18.
7. ELV 及び RoHS 適合品  
ELV & RoHS COMPLIANT.

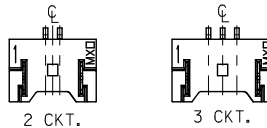
16.25	22.5	38.77	36.25	42.65	53780-3070	30	
8.75	22.5	26.27	23.75	30.15		-2070	
7.5	20	23.77	21.25	27.65		-1870	
6.25	16.25	20.02	17.5	23.9		-1570	
5	15	18.77	16.25	22.65		-1470	
3.75	12.5	16.27	13.75	20.15		-1270	
2.5	10	13.77	11.25	17.65		-1070	
2.5	8.75	12.52	10	16.4		-0970	
1.25	7.5	11.27	8.75	15.15		-0870	
1.25	6.25	10.02	7.5	13.9		-0770	
—	5	8.77	6.25	12.65		-0670	
—	3.75	7.52	5	11.4		-0570	
—	2.5	6.27	3.75	10.15		-0470	
—	—	5.02	2.5	8.9		-0370	
—	—	3.77	1.25	7.65		-0270	
E	D	C	B	A	53780-0270	2	
						EMBOSSED PACKAGE	CKT.
						オ-ダ-番号	ORDER No.
						種数	種数

REVISED EC NO. J2010-1927 DRAWN: SKUROSE 2010/03/25 CHKD: KAKAWA 2010/03/26 APPR: NIKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	CONNECTOR SERIES NO.	53780-**19	
	10 UNDER	± 0.2	MM ONLY	---	METRIC	THIRD ANGLE	PROJECTION	
	10 OVER 30 UNDER	± 0.25						
	30 OVER	± 0.3						
	ANGULAR	± 3 °						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART					
			DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT			
			CHECKED BY M. SASAO	DATE '04/04/15				
			APPROVED BY M. SASAO	DATE '04/04/15				
			MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
					SD-53780-003		1 OF 2	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

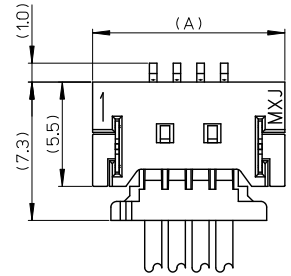
10 9 8 7 6 5 4 3 2 1



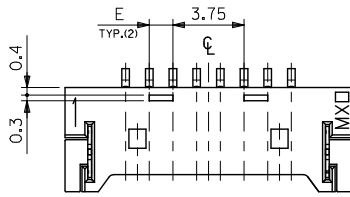
7~19極の奇数極に適用  
APPLY FOR ODD CIRCUITS OF 7~19



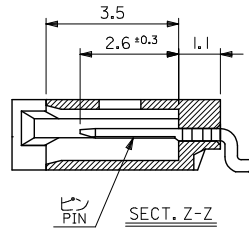
ロック形状図  
LOCK CONFIGURATION



嵌合図 (SCALE 5:1)  
MATED CONNECTORS (SCALE 5:1)



8~30極の偶数極に適用  
APPLY FOR EVEN CIRCUITS OF 8~30

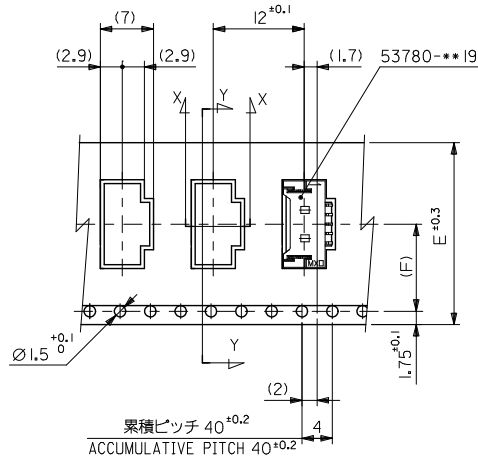
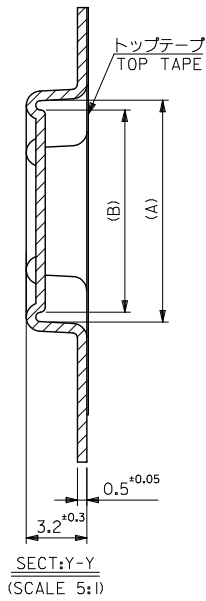


PIN SECT. Z-Z

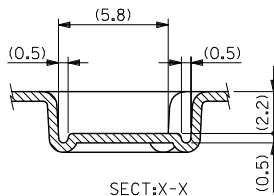
CONNECTOR SERIES NO. 53780-\*\*\*19

REVISED EC NO. J2010-1927 DRAWN:SKUROSE 2010/03/25 CHKD:KAKAWA 2010/03/26 APPR:MIKITA 2010/03/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT		
	10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/15	DOCUMENT NO. SD-53780-003		
	ANGULAR ± 3 °		MATERIAL NO.		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



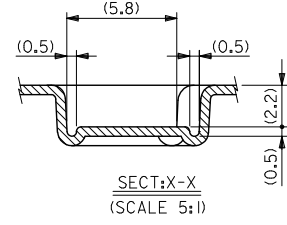
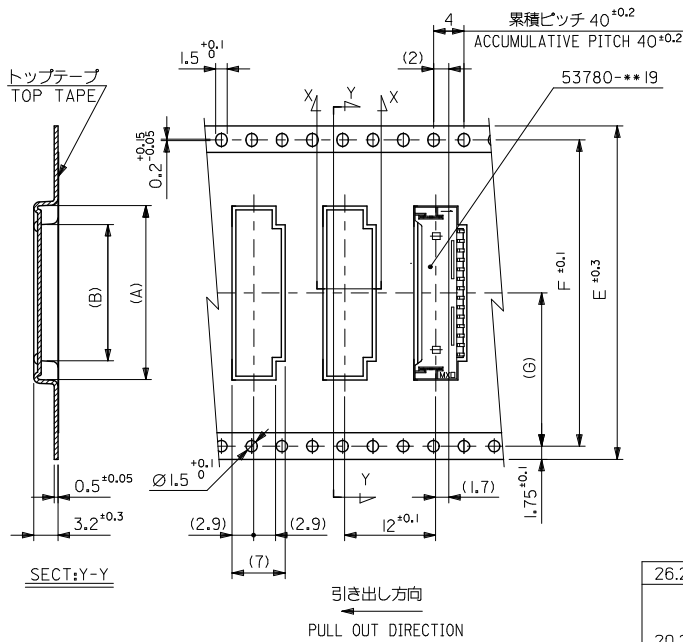
引き出し方向  
PULL OUT DIRECTION



11.5	24	29.4	25.4	11.75	16.7	53780-0970	9
				10.5	15.45	53780-0870	8
				9.25	14.2	53780-0770	7
				8	12.95	53780-0670	6
7.5	16	21.4	17.4	6.75	11.7	53780-0570	5
				5.5	10.45	53780-0470	4
				4.25	9.2	53780-0370	3
(F)	E	D	C	3	7.95	53780-0270	2
CARRIER TAPE WIDTH				(B)	(A)	MATERIAL NO.	標 識 C K T.

REVISED EC NO. J2010-0021 DRAWN/TAKASAKI 2009/07/07 CHKD/MHAYASHI 2009/07/08 APPR/MUKITA 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	MODEL NO.	53780-***70
	10 UNDER	± 0.2	MM ONLY	---	METRIC	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER	± 0.25	DRAWN BY T. UENO	DATE '04/04/15	TITLE	1.25 W/B WAFER ASSY EMBOSSSED TAPE PACKAGE	
	30 OVER	± 0.3	CHECKED BY M. SASAO	DATE '04/04/15	APPROVED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED
	ANGULAR ± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	SEE CHART	DOCUMENT NO.	SD-53780-004
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1



26.2	52.4	56	61.4	57.4	38	42.95	53780-3070	30
20.2	40.4	44	49.4	45.4	25.5	30.45	53780-2070	20
					25.5	27.95	53780-1870	18
					19.25	24.2	53780-1570	15
14.2	28.4	32	37.4	33.4	18	22.95	53780-1470	14
					15.5	20.45	53780-1270	12
(G)	F	E	D	C	(B)	(A)	MATERIAL NO.	編成 CKT.

<b>REVISED</b> IEC NO. J2010-0021 DRAWN BY: 2009/07/07 CHIKUMIYAKASAKI CHECKED BY: 2009/07/08 CHIKUMIYAKASHI APPROVED BY: 2009/07/08 APPR. NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 53780-***70
	10 UNDER ± 0.2	10 OVER 30 UNDER ± 0.25	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B WAFER ASSY EMBOSSED TAPE PACKAGE	
	30 OVER ± 0.3	ANGULAR ± 3 °	CHECKED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART	DATE '04/04/15	DOCUMENT NO. SD-53780-004	SHEET NO. 3 OF 3
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					